



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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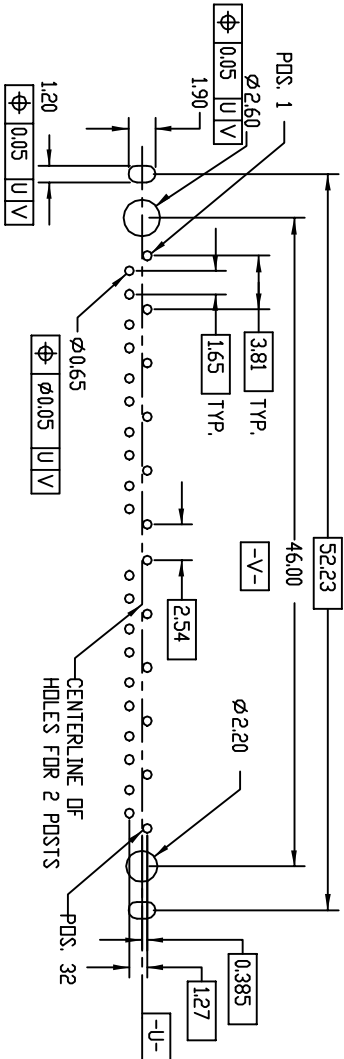
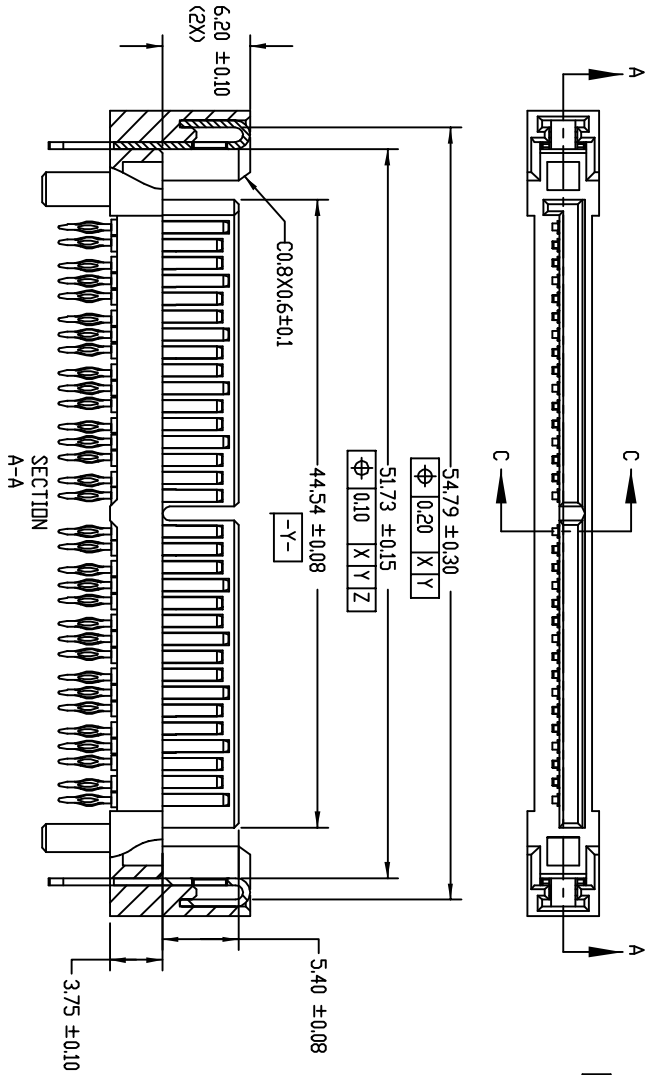




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PRODUCT NO.	PCB THICKNESS	DIMENSION 'A'	DIMENSION 'B'	DIMENSION 'C'	DIMENSION 'D'
10028542-001LF	1.57±0.10	2.75±0.20	3.20±0.10	3.65±0.10	1.43±0.10
10028542-002LF	3.18±0.10	4.35±0.20	4.80±0.10	3.65±0.10	1.43±0.10
10028542-003LF	1.57±0.10	2.75±0.20	3.20±0.10	2.10±0.10	0.79±0.10



NOTES

1. MATERIAL:  
HOUSING: HIGH TEMPERATURE PLASTIC, BLACK OR GRAY, UL94V-0  
CONTACT: COPPER ALLOY  
HOLD DOWN: COPPER ALLOY
2. FINISH:  
1.27µm MIN NICKEL UNDERPLATE OVERALL,  
1.91µm MIN TIN (LEAD-FREE) ON SOLDER TAIL,  
0.75µm MIN GOLD IN CONTACT AREA
3. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
4. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRARED OR VAPOR PHASE REFLOW OVEN
5. CONTACT W/P: 207 MIN FOR SIGNAL AND 252 MIN FOR GROUND

RECOMMENDED PCB LAYOUT  
(ALL TOLERANCES ARE ±0.05)

title	4 LANE VERTICAL PRESS FIT HEADER	Rev. B
catalog no	10028542	Rev. B
	CUSTOMER	Sheet 2 of 2